

40V N-Channel Enhancement Mode MOSFET

Description

The AP120N04T uses advanced trench technology

to provide excellent $R_{\text{DS}(\text{ON})},$ low gate charge and

operation with gate voltages as low as 10V. This

device is suitable for use as a Battery protection

or in other Switching application.

General Features

V_{DS} =40V I_D =120A

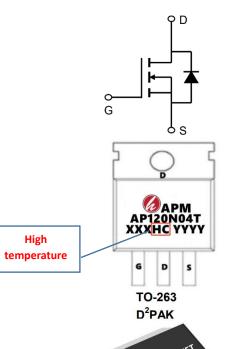
R_{DS(ON)} < 4.0mΩ @ V_{GS}=10V (Type: 2.9mΩ)

TSTG/ TJ: -55 to 175 ℃

Application

Load switch

Uninterruptible power supply



Package Marking and Ordering Information

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Product ID	Pack	Marking	Qty(PCS)
AP120N04T	TO-263-3L	AP120N04T XXXHC YYYY	800

Absolute Maximum Ratings (Tc=25°Cunless otherwise noted)

Symbol	Parameter	Rating	Units
VDS	Drain-Source Voltage	40	V
VGS	Gate-Source Voltage	±20	V
I⊳@Tc=25°C	Continuous Drain Current, V _{GS} @ 10V	120	А
I _D @T _C =75℃	Continuous Drain Current, V _{GS} @ 10V	105	А
I _D @T _C =100°C	Continuous Drain Current, V _{GS} @ 10V	84	A
IDM	Pulsed Drain Current	600	А
EAS	Single Pulse Avalanche Energy	272	mJ
IAS	Avalanche Current	40	А
P _D @T _C =25℃	Total Power Dissipation	180	W
TSTG	Storage Temperature Range	-55 to 175	°C
TJ	Operating Junction Temperature Range	-55 to 175	°C
R₀JA	Thermal Resistance Junction-Ambient	50	°C/W
R ₀ JC	Thermal Resistance Junction-Case ¹	0.78	°C/W



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Electrical Characteristics (TJ=25℃, unless otherwise noted)

Symbol	Parameter	Test Condition	Min.	Тур.	Max.	Units
V(BR)DSS	Drain-Source Breakdown Voltage	V _{GS} =0V, I _D =250µA	40	44	-	V
IDSS	Zero Gate Voltage Drain Current	V _{DS} =40V, V _{GS} =0V,	-	-	1.0	μA
IGSS	Gate to Body Leakage Current	V _{DS} =0V, V _{GS} = ±20V	-	-	±100	nA
VGS(th)	Gate Threshold Voltage	V _{DS} =V _{GS} , I _D =250µA	1.3	2.0	3.0	V
RDS(on)	Static Drain-Source on-Resistance	V _{GS} =10V, I _D =40A TC=25 $^{\circ}$ C	-	2.9	4.0	mΩ
RDS(on)	Static Drain-Source on-Resistance	$V_{GS}\text{=}10\text{V},I_{D}\text{=}40\text{A}$ TC=75 $^{\circ}\text{C}$		3.2	4.5	mΩ
RDS(on)	Static Drain-Source on-Resistance	V _{GS} =10V, I _D =40A TC=150℃		4.9	6.0	mΩ
RDS(on)	Static Drain-Source on-Resistance	V _{GS} =10V, I _D =40A TC=170℃		5.8	7.5	mΩ
Ciss	Input Capacitance		-	5734	-	pF
Coss	Output Capacitance	V _{DS} =20V, V _{GS} =0V, f=1.0MHz	-	686	-	pF
Crss	Reverse Transfer Capacitance		-	338	-	pF
Qg	Total Gate Charge		-	126	-	nC
Q_gs	Gate-Source Charge	$V_{DS}=20V, I_{D}=40A,$	-	24	-	nC
Q_{gd}	Gate-Drain("Miller") Charge	V _{GS} =10V f=1MHz	-	31	-	nC
td(on)	Turn-on Delay Time		-	20	-	ns
tr	Turn-on Rise Time	V_{GS} =10V, V_{DD} =20V,	-	106	-	ns
td(off)	Turn-off Delay Time	$R_{G_{ext}}=2.7\Omega$	-	68	-	ns
t _f	Turn-off Fall Time		-	112	-	ns
IS	Maximum Continuous Drain to Source Diode Forward Current		-	-	120	А
ISM	Maximum Pulsed Drain to Source Diode Forward Current		-	-	600	А
VSD	Drain to Source Diode Forward Voltage	V _{GS} =0V, I _S =30A	-	0.9	1.2	V
t _{rr}	Body Diode Reverse Recovery Time	TJ=25℃,	-	29	-	ns
Qrr	Body Diode Reverse Recovery Charge	l⊧=20A,dI/dt=100A/µs	-	28	-	nC

Note :

1、Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature

2 The EAS data shows Max. rating . The test condition is T_J= 25° C,V_DD=48V,V_G=10V,L=0.5mH,Rg= 25Ω ,I_As=40A

3、The data tested by pulsed , pulse width $\,\leq\,$ 300us , duty cycle $\,\leq\,$ 2%

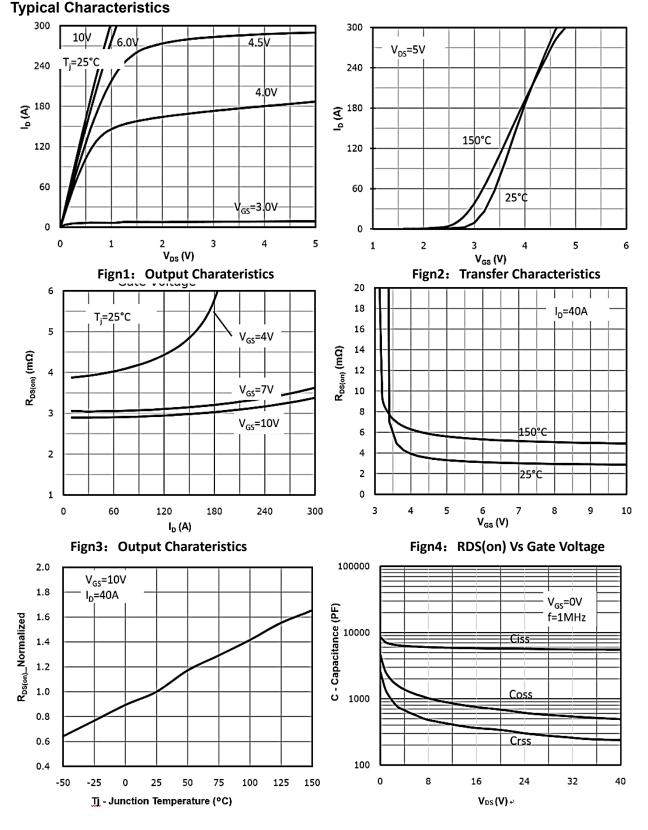
4. The power dissipation is limited by 150 $^\circ\!\mathrm{C}$ junction temperature

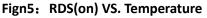
5. The data is theoretically the same as I D and I DM, in real applications, should be limited by total power dissipation.

6、Package limitation current is 180A



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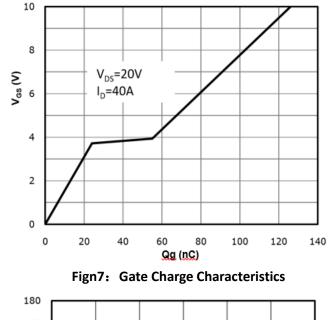


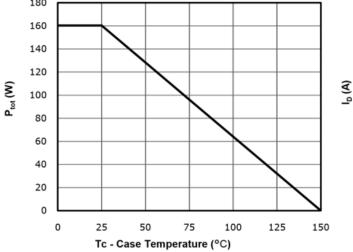


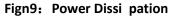
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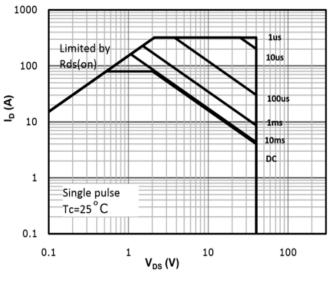


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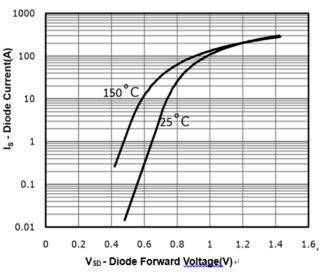




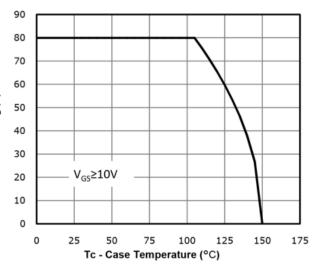




Fign11: Safe Operating Area



Fign8: Body-diode Forwared Characteristics

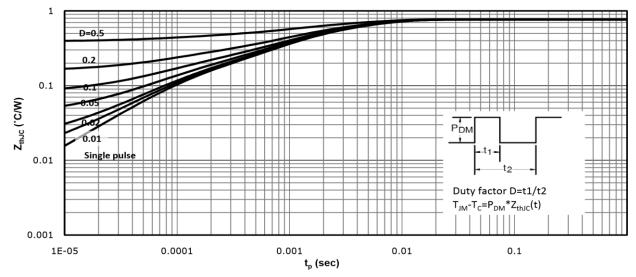


Fign10: Drain Curren Derating





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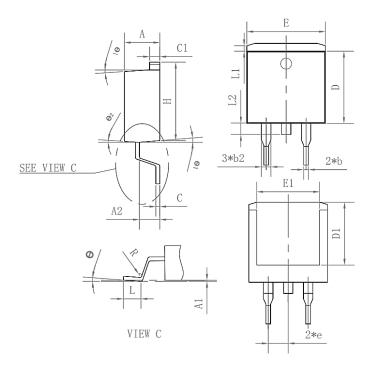


Fign12: Max. Transient Thermal Impedance

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40V N-Channel Enhancement Mode MOSFET Package Mechanical Data-TO-263-3L-SLK



		Common	
Symbol	mm		
	Mim	Nom	Max
А	4.35	4.47	4.60
A1	0.09	0.10	0.11
A2	2.30	2.40	2.70
b	0.70	0.80	1.00
b2	1.25	1.36	1.50
С	0.45	0.50	0.65
C1	1.29	1.30	9.40
D	9.10	9.20	9.30
D1	7.90	8.00	8.10
E	9.85	10.00	10.20
E1	7.90	8.00	8.10
Н	15.30	15.50	15.70
e	-	2.54	-
L	2.34	2.54	2.74
L1	1.00	1.10	1.20
L2	1.30	1.40	1.50
R	0.24	0.25	0.26
θ	0°	4 °	8°
Θ1	4 °	7 °	10°
Θ2	0°	3°	6°



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Edition	Date	Change
Rve1.0	2021/12/1	Initial release

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